



Layer	Base CU / Plt	Thick	Type	Stackup	Subs	Imp	Material	Dk	Df
Silkscreen		0.00					Taiyo-SS - White		
Soldermask		0.60					Taiyo-SM - Green	2.70	0.033
Lyr1	0.5oz / Std	1.80	S						
Prepreg		7.64					370HR - 2x2113	3.99	0.022
Lyr2	1oz	1.20	P						
Core		8.00					370HR - 8.0mils	4.61	0.021
Lyr3	1oz	1.20	S						
Prepreg		6.68					370HR - 2x2113	3.99	0.022
Lyr4	1oz	1.20	P						
Core		8.00					370HR - 8.0mils	4.61	0.021
Lyr5	1oz	1.20	P						
Prepreg		6.68					370HR - 2x2113	3.99	0.022
Lyr6	1oz	1.20	S						
Core		8.00					370HR - 8.0mils	4.61	0.021
Lyr7	1oz	1.20	P						
Prepreg		7.64					370HR - 2x2113	3.99	0.022
Lyr8	0.5oz / Std	1.80	S						
Soldermask		0.60					Taiyo-SM - Green	2.70	0.033
Silkscreen		0.00					Taiyo-SS - White		

Required Thickness

Type	Req. Thick	Tol% +	Tol% -	Act. Thick	Measured
Overall	62.0	10.0	10.0	64.6	
Over lamination	58.4	10.0	10.0	61.0	
Over laminate	57.2	10.0	10.0	59.8	
Over metal	60.8	10.0	10.0	63.4	

Bill of Materials

Material	Qty/Panel	Total Qty
8.0mils 1/1 core	3	3
0.5oz foil	2	2
2113 prepreg	8	8
White silkscreen	2	2
	15	15

Comments